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Automotive N-Channel 250 V (D-S) 175 °C MOSFET

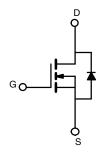


| PRODUCT SUMMARY | | | | | |
|---|--------|--|--|--|--|
| V _{DS} (V) | 250 | | | | |
| $R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$ | 0.1620 | | | | |
| $R_{DS(on)}$ (Ω) at $V_{GS} = 7.5 \text{ V}$ | 0.1800 | | | | |
| I _D (A) | 11.5 | | | | |
| Configuration | Single | | | | |
| Package | TO-252 | | | | |

FEATURES

- TrenchFET® power MOSFET
- Package with low thermal resistance
- 100 % R_q and UIS tested
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | | |
|--|-------------------------|-----------------------------------|-------------|------|--|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | | |
| Drain-source voltage | | V _{DS} | 250 | V | | |
| Gate-source voltage | | V _{GS} | ± 20 | V | | |
| Continuous drain current | T _C = 25 °C | 1 | 11.5 | | | |
| | T _C = 125 °C | I _D | 6.6 | | | |
| Continuous source current (diode conduction) a | | Is | 50 | Α | | |
| Pulsed drain current ^b | | I _{DM} | 30 | | | |
| Single pulse avalanche current | L = 0.1 mH | I _{AS} | 10 | | | |
| Single pulse avalanche energy | L=0.11IIII | E _{AS} | 5 | mJ | | |
| Maximum power dissipation ^b | T _C = 25 °C | р | 62 | W | | |
| | T _C = 125 °C | P _D | 20 | VV | | |
| Operating junction and storage temperature | e range | T _J , T _{stg} | -55 to +175 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | |
|----------------------------|-------------|------------|-------|------|--|--|
| PARAMETER | | SYMBOL | LIMIT | UNIT | | |
| Junction-to-ambient | PCB mount c | R_{thJA} | 50 | °C/W | | |
| Junction-to-case (drain) | · | | 2.4 | C/VV | | |

Notes

- a. Package limited
- b. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- c. When mounted on 1" square PCB (FR4 material)



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| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT | |
|--|----------------------|---|--|------|--------|--------|------|--|
| Static | | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | | 250 | - | - | V | |
| Gate-source threshold voltage | V _{GS(th)} | V _{DS} = | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ | | 3.0 | 3.5 | V | |
| Gate-source leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | - | - | ± 100 | nA | |
| | I _{DSS} | $V_{GS} = 0 V$ | V _{DS} = 250 V | - | - | 1 | μA | |
| Zero gate voltage drain current | | V _{GS} = 0 V | V _{DS} = 250 V, T _J = 125 °C | - | - | 50 | | |
| | | V _{GS} = 0 V | V _{DS} = 250 V, T _J = 175 °C | - | - | 250 | μΑ | |
| On-state drain current ^a | I _{D(on)} | V _{GS} = 10 V | $V_{DS} \ge 5 V$ | 12 | - | - | Α | |
| | • • | V _{GS} = 10 V | I _D = 12 A | - | 0.1342 | 0.1620 | 1 | |
| During and a solution of the s | Б | V _{GS} = 7.5 V | I _D = 10 A | - | 0.1443 | 0.1800 | Ω | |
| Drain-source on-state resistance a | R _{DS(on)} | V _{GS} = 10 V | I _D = 12 A, T _J = 125 °C | - | - | 0.3437 | | |
| | | V _{GS} = 10 V | I _D = 12 A, T _J = 175 °C | = | - | 0.4560 | | |
| Forward transconductance b | 9 _{fs} | V _{DS} = 15 V, I _D = 12 A | | = | 12 | - | S | |
| Dynamic ^b | | • | | | 1 | ı | ı | |
| Input capacitance | C _{iss} | | V _{DS} = 25 V, f = 1 MHz | - | 558 | 785 | pF | |
| Output capacitance | C _{oss} | $V_{GS} = 0 V$ | | - | 308 | 435 | | |
| Reverse transfer capacitance | C _{rss} | 1 | | = | 11 | 16 | | |
| Total gate charge ^c | Qq | | | | 10.6 | 16 | | |
| Gate-source charge c | Q _{gs} | V _{GS} = 10 V | $V_{DS} = 125 \text{ V}, I_{D} = 10 \text{ A}$ | - | 3.1 | - | nC | |
| Gate-drain charge ^c | Q _{qd} | 1 | | = | 2.8 | - | | |
| Gate resistance | R _q | f = 1 MHz | | 1.9 | 3.8 | 5.7 | Ω | |
| Turn-on delay time c | t _{d(on)} | V_{DD} = 125 V, R_L = 12.5 Ω I_D \cong 10 A, V_{GEN} = 10 V, R_g = 1 Ω | | = | 8 | 20 | | |
| Rise time ^c | t _r | | | =. | 3 | 10 | - ns | |
| Turn-off delay time ^c | t _{d(off)} | | | = | 15 | 30 | | |
| Fall time c | t _f | | | = | 3 | 10 | | |
| Source-Drain Diode Ratings and Charac | cteristics b | | | | | | 1 | |
| Pulsed current a | I _{SM} | | | - | - | 30 | Α | |
| Forward voltage | V _{SD} | I _F = 15 A, V _{GS} = 0 V | | - | 0.9 | 1.5 | V | |
| Body diode reverse recovery time | t _{rr} | I _F = 10 A, di/dt = 100 A/μs | | - | 127 | 260 | ns | |
| Body diode reverse recovery charge | Q _{rr} | | | - | 583 | 1170 | nC | |
| Reverse recovery fall time | t _a | | | - | 88 | - | | |
| Reverse recovery rise time | t _b | | | _ | 39 | - | ns | |
| Body diode peak reverse recovery current | I _{RM(REC)} | | | _ | -8.6 | _ | Α | |

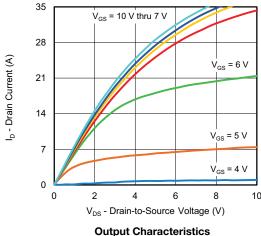
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

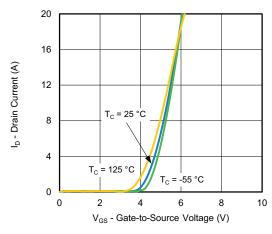
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



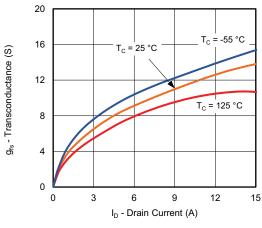
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



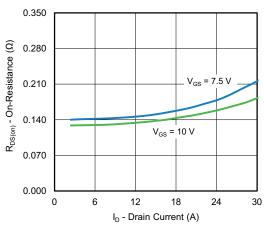




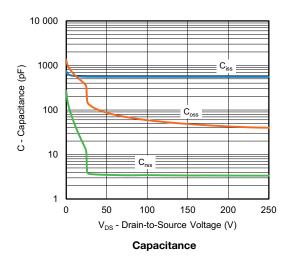
Transfer Characteristics

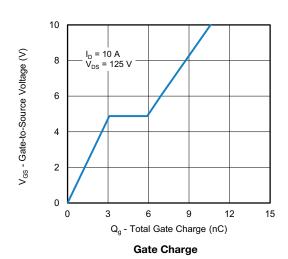


Transconductance



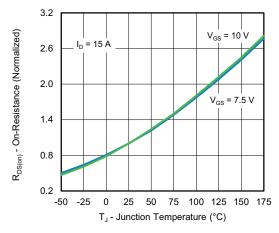
On-Resistance vs. Drain Current



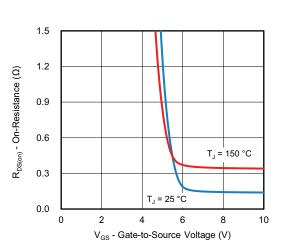




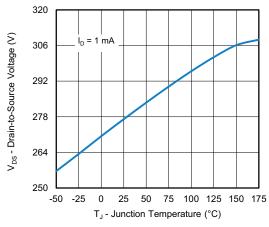
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature



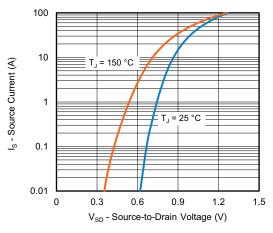
On-Resistance vs. Gate-to-Source Voltage



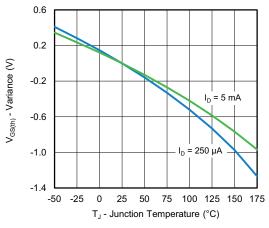
Drain Source Breakdown vs. Junction Temperature

Note

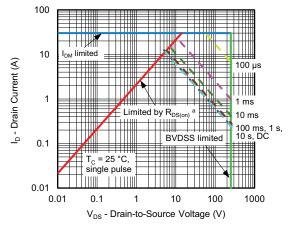
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



Source Drain Diode Forward Voltage



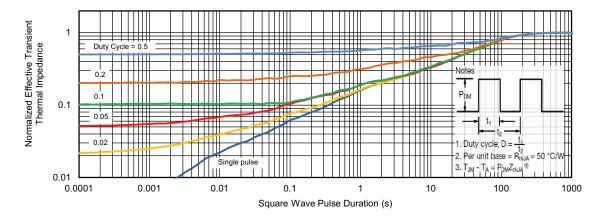
Threshold Voltage



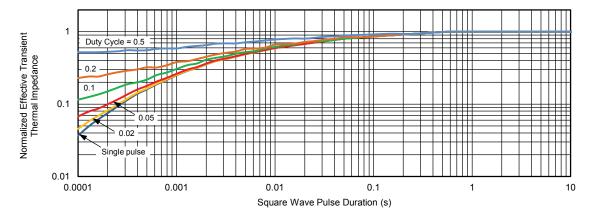
Safe Operating Area



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

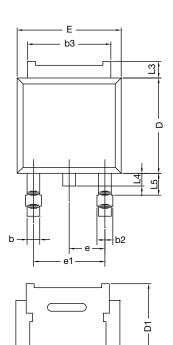
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

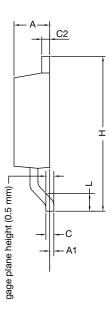
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TO-252AA Case Outline





| | MILLIN | IETERS | INCHES | | |
|--|--------|--------|-----------|-------|--|
| DIM. | MIN. | MAX. | MIN. | MAX. | |
| Α | 2.18 | 2.38 | 0.086 | 0.094 | |
| A1 | - | 0.127 | - | 0.005 | |
| b | 0.64 | 0.88 | 0.025 | 0.035 | |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 | |
| С | 0.46 | 0.61 | 0.018 | 0.024 | |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| D1 | 4.10 | - | 0.161 | - | |
| E | 6.35 | 6.73 | 0.250 | 0.265 | |
| E1 | 4.32 | - | 0.170 | - | |
| Н | 9.40 | 10.41 | 0.370 | 0.410 | |
| е | 2.28 | BSC | 0.090 BSC | | |
| e1 | 4.56 | BSC | 0.180 BSC | | |
| L | 1.40 | 1.78 | 0.055 | 0.070 | |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L4 | - | 1.02 | - | 0.040 | |
| L5 | 1.01 | 1.52 | 0.040 | 0.060 | |
| ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019 | | | | | |

DWG: 6019

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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ATTLICATION NOT



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